

Dual 450mA LDO REGULATOR

DESCRIPTION

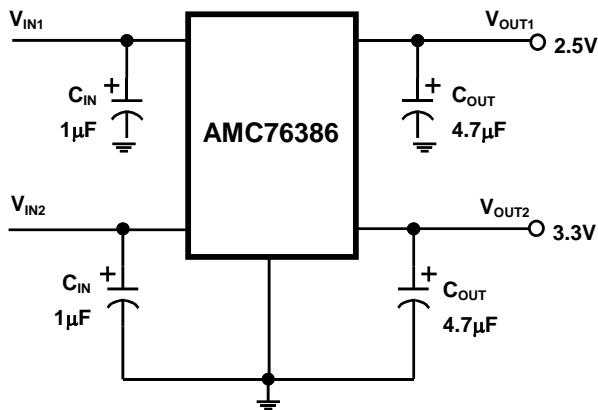
The AMC76386 series is a low dropout regulator rated for 450mA output current. Low power consumption and high accuracy is achieved through CMOS technology and internal trimmed reference voltage.

The AMC76386 series consists of a high-precision voltage reference, error correction circuit, and a current limit output driver. The fast transient response is an outstanding feature for applications with various loads.

FEATURES

- 2% internally trimmed output
- Output current is excess of 450mA
- Input-Output differential of typ. 360mV
- at 300mA & low quiescent current of 10µA typical
- P-MOS output stage with low RdsON.
- Short circuit protection
- Internal thermal overload protection
- Available in SOP-8 package

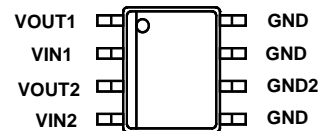
TYPICAL APPLICATION CIRCUIT



APPLICATIONS

- CD ROM, DVD
- Wireless Communication Systems
- Digital Camera
- Battery Powered Applications

PACKAGE PIN OUT



**8-Pin Plastic SOP-8
Surface Mount
(Top View)**

ORDER INFORMATION

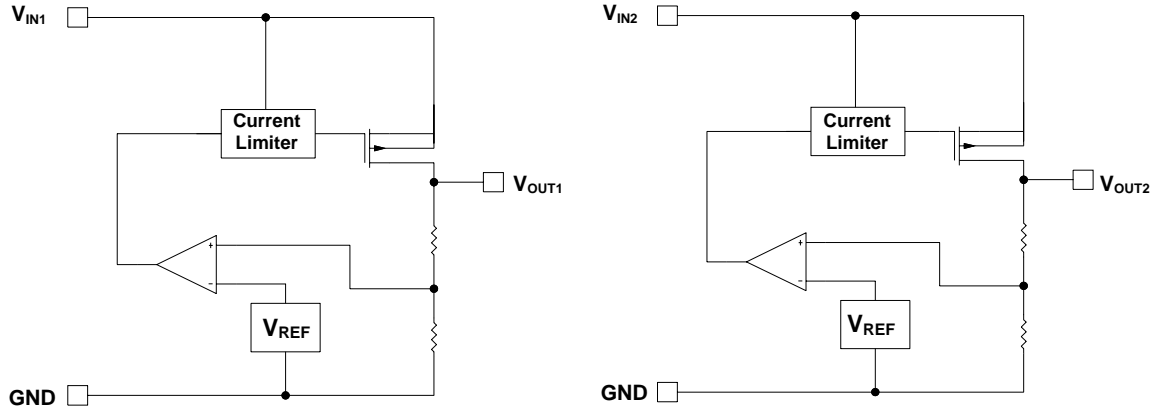
| | | |
|---|---------------------------------|------------------------|
| T_A (°C) | DM | Plastic SOP-8 8-pin |
| -40 to 85 | AMC76386-DMF (Lead Free) | |
| Note: 1.All surface-mount packages are available in Tape & Reel. Append the letter "T" to part number (i.e. AMC76386DMFT). 2.The letter "F" is marked for Lead Free process. | | |

ABSOLUTE MAXIMUM RATINGS

| | |
|---|----------------|
| Input Voltage, V_{IN1} , V_{IN2} | 13V |
| Maximum Operating Junction Temperature, T_J | 150°C |
| Storage Temperature Range | -65°C to 150°C |
| Lead Temperature (soldering, 10 seconds) | 260°C |
| Note: Exceeding these ratings could cause damage to the device. All voltages are with respect to Ground. Currents are positive into, negative out of the specified terminal. | |

POWER DISSIPATION TABLE

| Package | θ_{JA} (°C/W) | Derating factor (mW/°C) $T_A \geq 25^\circ\text{C}$ | $T_A \leq 25^\circ\text{C}$ Power rating (mW) | $T_A = 70^\circ\text{C}$ Power rating (mW) |
|--|-------------------------|--|--|---|
| DM | 165(Note) | 6 | 757 | 487 |
| Note: $T_J = T_A + (P_D \times \theta_{JA})$ P_D : Total Power dissipation. θ_{JA} : Thermal resistance from Junction to Ambient. The θ_{JA} numbers are guidelines for the thermal performance of the device/PC-board system. All of the above assume no ambient airflow. | | | | |

BLOCK DIAGRAM


RECOMMENDED OPERATING CONDITIONS

| Parameter | Symbol | Recommended Operating Conditions | | | Units |
|--|----------|----------------------------------|------|------|--------------|
| | | Min. | Typ. | Max. | |
| Input Voltage | V_{IN} | 3.0 | | 10 | V |
| Load Current (with adequate heat sinking) | I_o | 5 | | 450 | mA |
| Input Capacitor (V_{IN} to GND) | | 0.1 | | | μ F |
| Output Capacitor with ESR of 10 Ω max., (V_{OUT} to GND) | | 1.0 | | | μ F |
| Operating ambient temperature range | T_A | -40 | | 85 | $^{\circ}$ C |
| Operating junction temperature | T_J | | | 125 | $^{\circ}$ C |

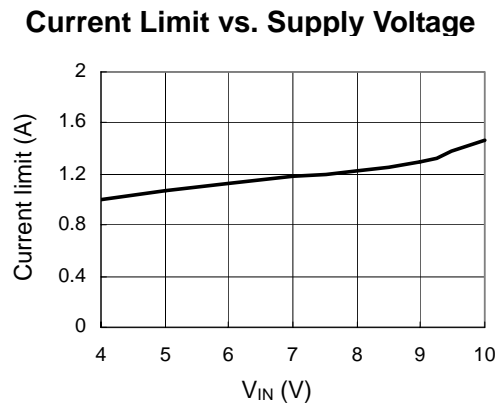
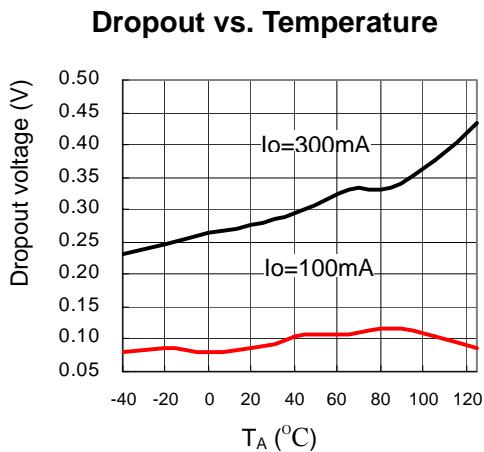
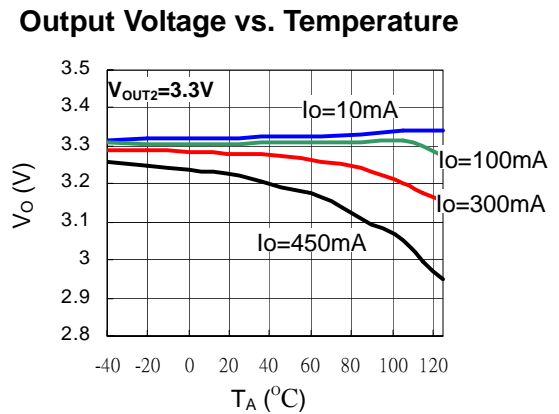
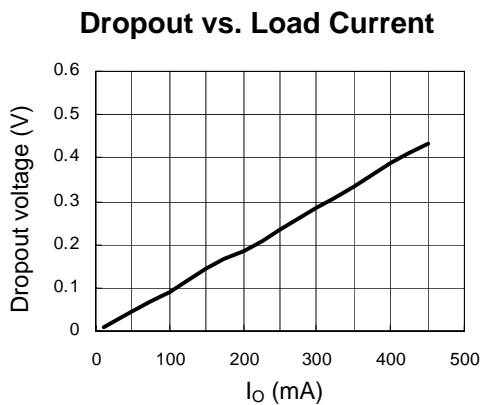
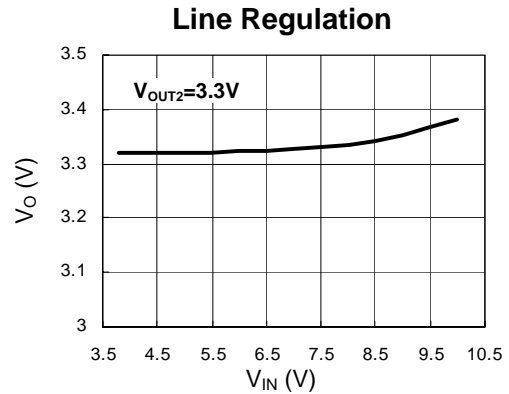
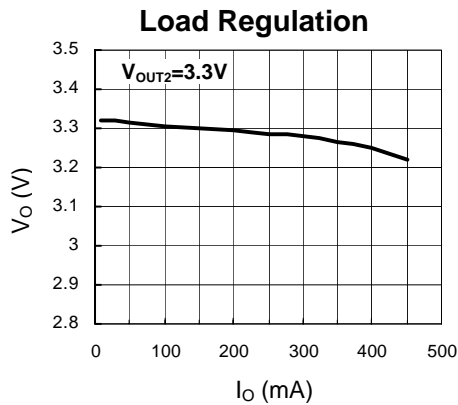
ELECTRICAL CHARACTERISTICS

Unless otherwise specified, $V_{IN} = V_{OUT(TYP)} + 1V$, $I_o = 10mA$, $C_{OUT} = 4.7\mu F$, $T_A = 25^{\circ}C$, and are for DC characteristics only. (Low duty cycle pulse testing techniques are used which maintains junction and case temperatures equal to the ambient temperature.)

| Parameter | | Symbol | Test Conditions | AMC76386 | | | Units |
|--|------------|-----------------|--|----------|-----------|-------|------------------|
| | | | | Min | Typ | Max | |
| Output Voltage | V_{OUT1} | V_o | $I_o = 10mA$ | 2.450 | 2.500 | 2.550 | V |
| | V_{OUT2} | | | 3.234 | 3.300 | 3.366 | |
| Line Regulation | | ΔV_{OI} | $V_{IN} = (V_{OUT} + 0.5V)$ to 8V | | 0.1 | 0.3 | %/V |
| Load regulation | | ΔV_{OL} | $10mA \leq I_o \leq 100mA$ | | 15 | 30 | mV |
| | | | $10mA \leq I_o \leq 300mA$ | | 45 | 80 | |
| | | | $10mA \leq I_o \leq 450mA$ | | 95 | 140 | |
| Dropout Voltage | | ΔV | $I_o = 100mA$ | | 120 | 180 | mV |
| | | | $I_o = 300mA$ | | 360 | 540 | |
| | | | $I_o = 450mA$ | | 540 | 810 | |
| Ground Pin Current | | I_Q | $I_o = 10mA \sim 450mA$ | | 8 | 20 | μ A |
| Current Limit | | I_{CL} | $V_{IN} = V_{OUT} + 0.5V$ | 450 | | | mA |
| Output Voltage Temperature Coefficient | | | $I_o = 100mA, -40^{\circ}C \leq T_J \leq 125^{\circ}C$ | | ± 100 | | ppm/ $^{\circ}C$ |

CHARACTERIZATION CURVES

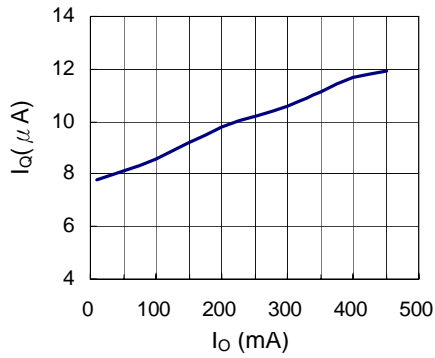
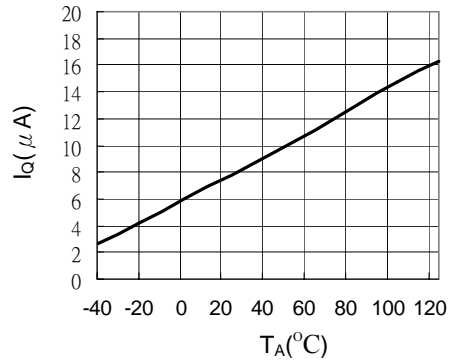
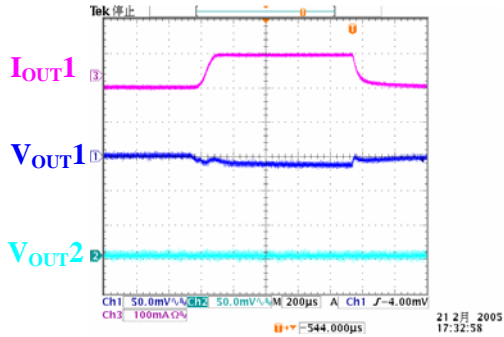
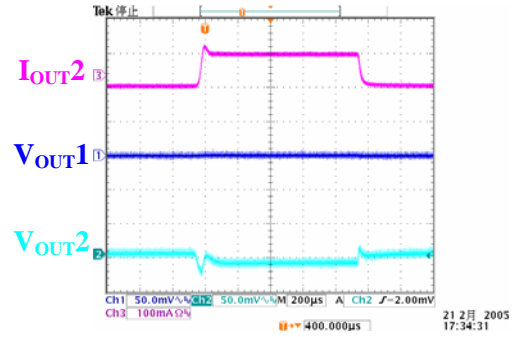
Typical Performance Characteristics

 ($V_{IN}=5V$, $C_{IN}=1\mu F$, $C_{OUT}=4.7\mu F$, $T_A=25^\circ C$ unless otherwise specified.)


CHARACTERIZATION CURVES (Continued)

Typical Performance Characteristics

 $V_{IN}=5V$, $C_{IN}=1\mu F$, $C_{OUT}=4.7\mu F$, $T_A=25^\circ C$ unless otherwise specified.

Quiescent Current vs. Load

Quiescent Current vs. Temperature

Load Transient Regulation

Load Transient Regulation


Application Note:
The maximum power dissipation of a single-output regulator:

$$P_{D(MAX)} = [(V_{IN(MAX)} - V_{OUT(NOM)}) \times I_{OUT(NOM)} + V_{IN(MAX)} \times I_Q]$$

$V_{OUT(NOM)}$ = the nominal output voltage
 $I_{OUT(NOM)}$ = the nominal output current, and
 I_Q = the quiescent current the regulator consumes at $I_{OUT(MAX)}$
 $V_{IN(MAX)}$ = the maximum input voltage

Thermal consideration:

The AMC76386 series have internal power and thermal limiting circuitry designed to protect the device under overload conditions. However maximum junction temperature ratings should not be exceeded under continuous normal load conditions. The thermal protection circuit of AMC76386 series will prevent the device from damage due to excessive power dissipation. When the device temperature rises to approximately 150°C, the regulator will be turned off.

When power consumption is over about 487mW (SOP-8 package, at $T_A=70^\circ\text{C}$), additional heat sink is required to control the junction temperature below 125°C.

The junction temperature is: $T_J = P_D (\theta_{JT} + \theta_{CS} + \theta_{SA}) + T_A$

P_D : Total Dissipated power.

θ_{JT} : Thermal resistance from the junction to the mounting tab of the package.

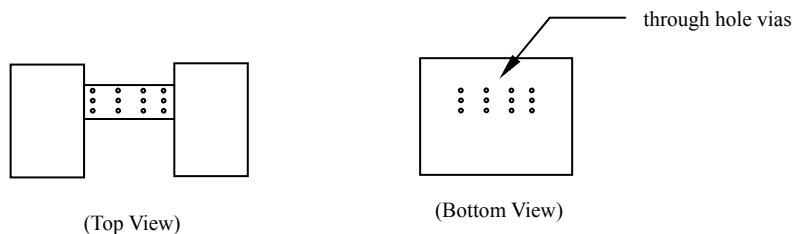
θ_{CS} : Thermal resistance through the interface between the IC and the surface on which it is mounted.
(typically, $\theta_{CS} < 1.0^\circ\text{C/W}$)

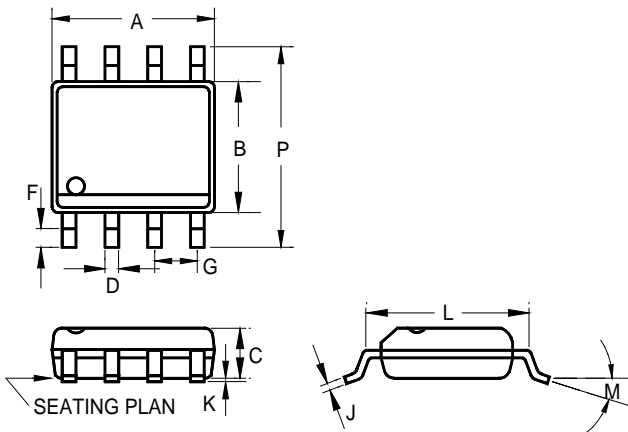
θ_{SA} : Thermal resistance from the mounting surface to ambient (thermal resistance of the heat sink).

If PC Board copper is going to be used as a heat sink, below table can be used to determine the appropriate size of copper foil required. For multi-layered PCB, these layers can also be used as a heat sink. They can be connected with several through hole vias.

| | | | | | | | |
|--|-----|------|------|------|------|------|------|
| PCB θ_{SA} ($^\circ\text{C/W}$) | 59 | 45 | 38 | 33 | 27 | 24 | 21 |
| PCB heat sink size (mm^2) | 500 | 1000 | 1500 | 2000 | 3000 | 4000 | 5000 |

Recommended figure of PCB area used as a heat sink.



PACKAGE
8-Pin Surface Mount SOP-8


| | INCHES | | | MILLIMETERS | | |
|---|-----------|-----|-------|-------------|-----|------|
| | MIN | TYP | MAX | MIN | TYP | MAX |
| A | 0.183 | - | 0.202 | 4.65 | - | 5.13 |
| B | 0.144 | - | 0.163 | 3.66 | - | 4.14 |
| C | 0.068 | - | 0.074 | 1.73 | - | 1.88 |
| D | 0.010 | - | 0.020 | 0.25 | - | 0.51 |
| F | 0.015 | - | 0.035 | 0.38 | - | 0.89 |
| G | 0.050 BSC | | | 1.27 BSC | | |
| J | 0.007 | - | 0.010 | 0.19 | - | 0.25 |
| K | 0.005 | - | 0.010 | 0.13 | - | 0.25 |
| L | 0.189 | - | 0.205 | 4.80 | - | 5.21 |
| M | - | - | 8° | - | - | 8° |
| P | 0.228 | - | 0.244 | 5.79 | - | 6.20 |

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